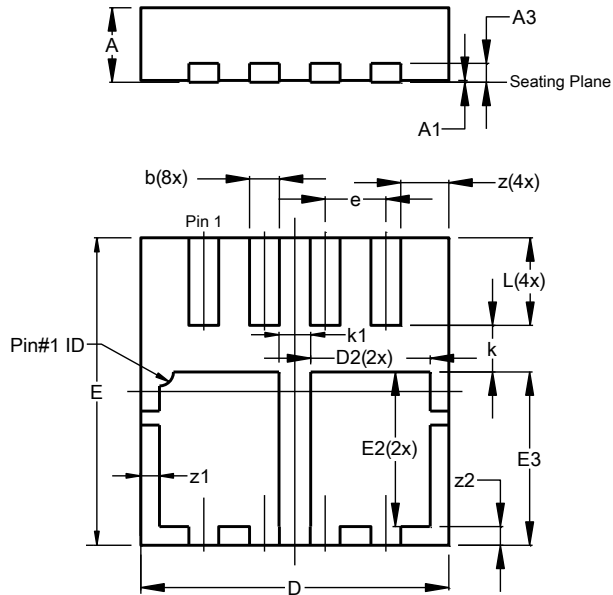


Package Outline Dimensions

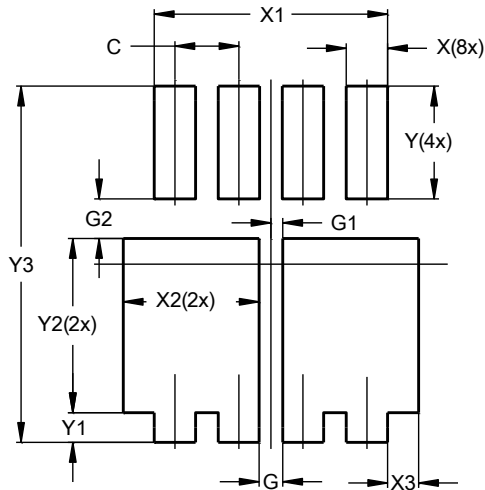
PowerDI3333-8 (Type E)



PowerDI3333-8 (Type E)			
Dim	Min	Max	Typ
A	0.750	0.850	0.800
A1	0.00	0.05	0.02
A3	--	--	0.203
b	0.27	0.37	0.32
D	3.25	3.35	3.30
D2	1.18	1.38	1.28
E	3.25	3.35	3.30
E2	1.56	1.76	1.66
e	0.65BSC		
k	--	--	0.50
k1	0.25	--	--
L	0.84	1.04	0.94
z	--	--	0.515
z1	--	--	0.20
z2	--	--	0.20
All Dimensions in mm			

Suggested Pad Layout

PowerDI3333-8 (Type E)



Dimensions	Value (in mm)
C	0.650
G	0.240
G1	0.120
G2	0.400
X	0.420
X1	2.370
X2	1.380
X3	0.315
Y	1.140
Y1	0.300
Y2	1.760
Y3	3.600

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.